

## Transient Voltage Suppressors for ESD Protection

### General Description

The LESD9D3.3CT5G is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space is at a premium.

### Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

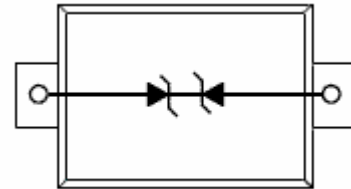
### Features

- Small Body Outline Dimensions
- Low Body Height
- Peak Power up to 150 Watts @ 8 x 20  $\mu$ s Pulse
- Low Leakage current
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000-4-4 Level 4 EFT Protection

LESD9D3.3CT5G



SOD-923



### Ordering information

Device	Marking	Shipping
LESD9D3.3CT5G	B	8000/Tape&Reel

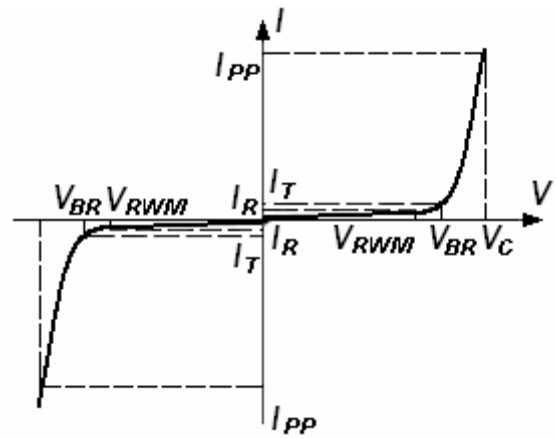
### Absolute Ratings ( $T_{amb}=25^{\circ}\text{C}$ )

Symbol	Parameter	Value	Units
$P_{PP}$	Peak Pulse Power ( $t_p = 8/20 \mu$ s)	150	W
$T_L$	Maximum lead temperature for soldering during 10s	260	$^{\circ}\text{C}$
$T_{stg}$	Storage Temperature Range	-55 to +155	$^{\circ}\text{C}$
$T_{op}$	Operating Temperature Range	-40 to +125	$^{\circ}\text{C}$
$T_j$	Maximum junction temperature	150	$^{\circ}\text{C}$
	IEC61000-4-2 (ESD) air discharge	$\pm 15$	KV
	IEC61000-4-4 (EFT) contact discharge	$\pm 8$	KV
	ESD Voltage Per Human Body Model	40	A
		16	KV

# LESD9D3.3CT5G

## Electrical Parameter

Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$I_T$	Test Current
$V_{BR}$	Breakdown Voltage @ $I_T$



## Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. VF = 0.9V at IF = 10mA

Device	$V_{RWM}$ (V)	$I_R$ (uA) @ $V_{RWM}$	$V_{BR}$ (V) @ $I_T$ (Note 1)	$I_T$	$V_C$ (V) @ $I_{PP}=5 A^*$	$V_C$ (V) @ Max $I_{PP}^*$	$I_{PP}$ (A)*	$P_{PK}$ (W)*	C (pF)
	Max	Max	Min	mA	Typ	Max	Max	Max	Typ
LESD9D3.3CT5G	3.3	1	5.0	1.0	8.4	14.1	11.2	158	25

\*Surge current waveform per Figure 1.

- $V_{BR}$  is measured with a pulse test current  $I_T$  at an ambient temperature of 25°C.

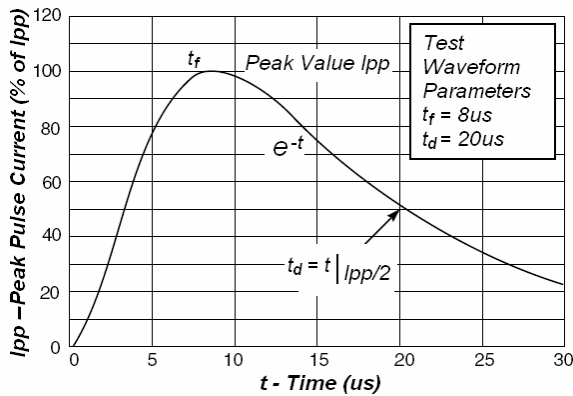


Fig1. Pulse Waveform

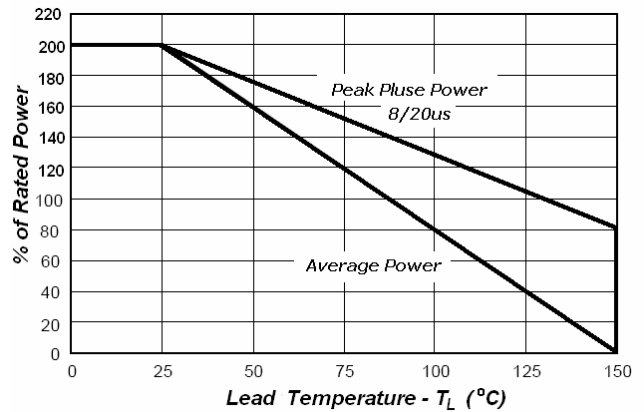
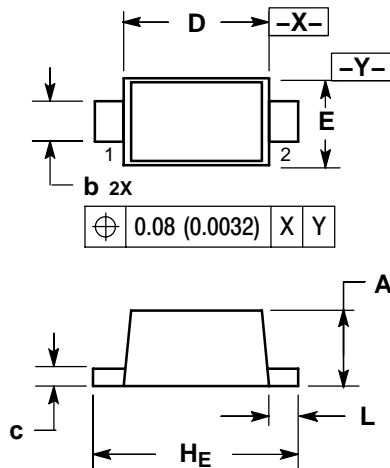


Fig2. Power Derating Curve

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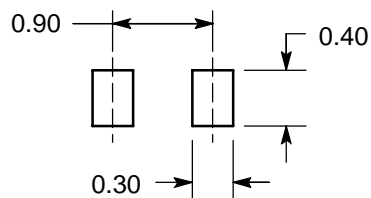


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.34	0.37	0.40	0.013	0.015	0.016
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
$H_E$	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

### SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS